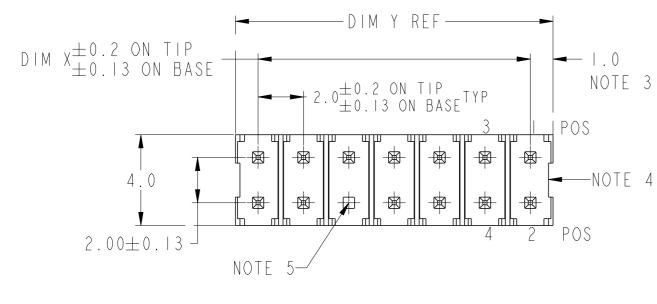
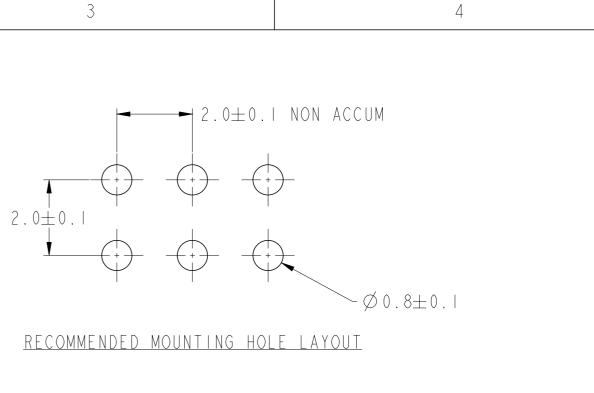
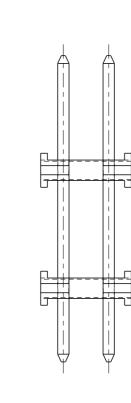
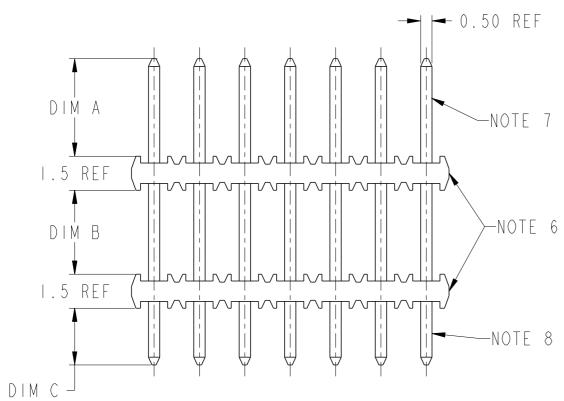
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tolerance std				eng Yuan-Yuan Bao		D 2020/10/26				1	
ISO 406	TOLERANCES U OTHERWISE SPE			chr	-		-		\blacksquare		1
ISO 0				appr	Tim Yao		2020/12/24 p		product	fami	ily
	linear	0.X	± -	A	hanal	→ MINITEK II → D/D STD HDD (HIGH STANDOFE)					
surface -/		0.XX	±0.25	25 A III							
		0.XXX	± -	1	FUI	+ R/F	STR	HDR (H	IGH STA	NDOF	F)
ISO I302	angular	0°	± 3°			cat. no).		-		Р
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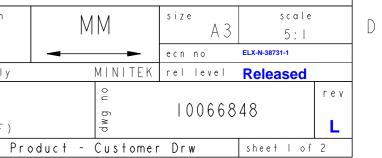
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Creo File - REV E - 2016-02-12



STATUS:Released

Printed: Dec 24, 2020

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PRODUCT NO.	POS	DIM X	DIM Y	DIM A	DIM B	DIM C	POL PO	S	
0066848-X01LF	2 X I I	20	22	4.3	3.7	2.5±0.25	-		
- X 0 2 L F	2XI7	32	34	4.3	3.7	2.5±0.25	-		
- X O 3 L F	2 X I O	8	20	4.3	3.7	2.5±0.25	_		
- X 0 4 L F	2 X 5	8	10	6.4	7.6	2.2±0.25	-		
-X05LF	2 X 7	12	4	4.3	3.7	2.5±0.25	-		
- X 0 6 L F	2 X 5	8	10	4.3	3.7	2.5±0.25	-		
- X 0 7 L F	2 X I 2	22	24	4.3	3.7	2.5±0.25	-		
- X 0 8 L F	2 x 4	6	8	3.4	11.2	2.5±0.25	-		

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NOTES:

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- I. MATERIAL: BODY : HIGH TEMPERATURE THERMOPLASTIC, UL 94V-O BLACK PIN : COPPER ALLOY
- 2. TOLERANCE UNLESS OTHERWISE NOTED \pm 0.25
- 3. DIM 1.0 \pm 0.15 FOR MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN. DIM 1.5 MAX APPLIES
- 4. RECESS APPLIES TO MOLDED SIDE(S) ONLY.
- 5. POLARISATION BY OMISSION OF PIN. POSITION REFER TO TABLE
- 6. MOLDED SIDES OF HSG TO BE ON THE SAME END FOR STACKABILITY - APPLICABLE FOR SPECIFIC P/N.
- 7. PLATING ON MATING LENGTH: -IXX --- 0.76um GXT OVER I.27um MIN NICKEL UNDERPLATE. -2XX --- I.27um GXT OVER I.27um MIN NICKEL UNDERPLATE. -3XX --- 0.38um GXT OVER 1.27um MIN NICKEL UNDERPLATE.

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- 8. SOLDER TAIL PLATING:
 - a) 3.81um MIN TIN/LEAD (90/10) PLATING OVER 1.27um MIN NICKEL UNDERPLATE.
 - b) 2.54um MIN 100% MATTE TIN PLATING OVER 1.27um MIN NICKEL UNDERPLATE.
- 9. PRODUCT DESCRIPTION CODE: XXXXXXX - XXX X LF

-EXTENSION NUMBER BASE NUMBER

- IO. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR IO SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

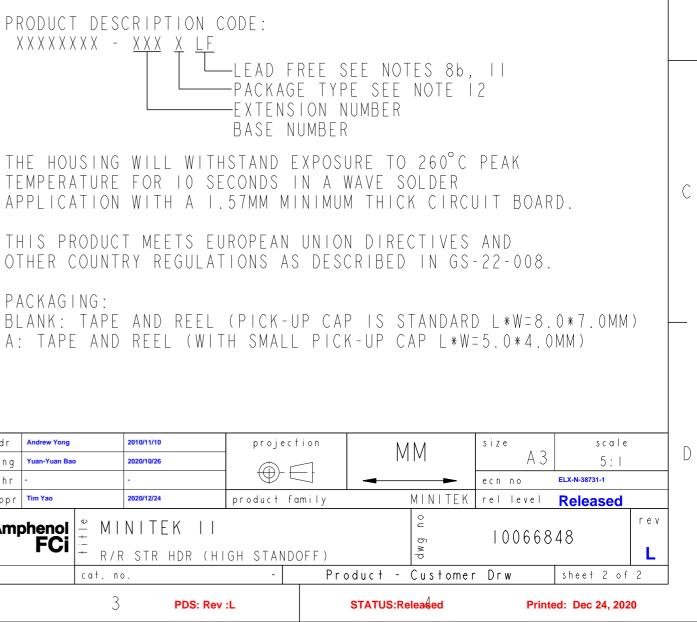
PACKAGING: 12

A: TAPE AND REEL (WITH SMALL PICK-UP CAP L*W=5.0*4.0MM)

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eng	Yuan-Yuan Bao			2020/10/26				\bigcirc	_	-
chr	-			-						J
ppr	Tim Yao		:	2020/12/24			pro	duc t	fa	mil
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